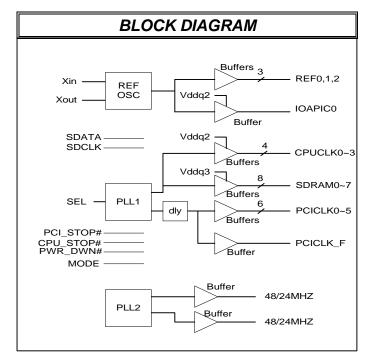


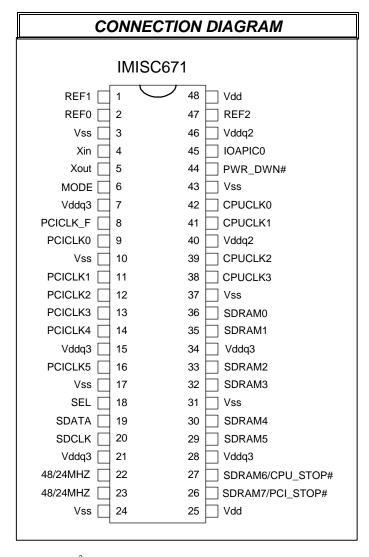
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PRODUCT FEATURES

- Supports Pentium & Pro CPUs.
- 4 CPU clocks up to 8 loads.
- Up to 8 SDRAM clocks for 2 DIMs.
- Supports Power Savings Frequencies.
- 7 PCI synchronous clocks.
- Optional common or mixed supply mode:
- (Vdd = Vddq3 = Vddq2 = 3.3V) or
- (Vdd = Vddq3 = 3.3V, Vddq2 = 2.5V)
- < 250ps skew CPU and SDRAM clocks.
- < 250ps skew among PCI clocks.
- I²C 2-Wire serial interface
- Programmable registers featuring:
 - enable/disable each output pin
 - mode as tri-state, test, or normal
 - 24/48 MHz selections
- 1 IOAPIC clock for multiprocessor support.
- 48-pin SSOP package



| FREQUENCY TABLE | | | | | | |
|-----------------|------|------|--|--|--|--|
| SEL CPU PCI | | | | | | |
| 0 | 60.0 | 30.0 | | | | |
| 1 | 66.6 | 33.3 | | | | |



Purchase of I²C components of International Microcircuits, Inc. or one of its sublicensed Associated Companies conveys a license under the Philips I²C Patent Rights to use these components in an I²C system, provided that the system conforms to the I²C Standard Specification as defined by Philips.



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PIN DESCRIPTION

Xin, Xout - These pins form an on-chip reference oscillator when connected to terminals of an external parallel resonant crystal (nominally 14.318 MHz). Xin may also serve as input for an externally generated reference signal.

SEL - Standard frequency select input. It has internal pull-up.

CPUCLK(0:3) - Low skew (<250 pS) clock outputs for host frequencies such as CPU, Chipset, Cache. Vddq2 is the supply voltage for these outputs.

SDRAM(0:5) - Synchronous DRAM DIMs clocks. They are powered by Vddq3.

SDRAM6/CPU_STOP# - If MODE=1, this pin is a Synchronous DRAM DIMs clock output powered by Vddq3. If MODE=0, this pin is a CPU_STOP# input signal, where a low level stops the CPU however, the SDRAM clocks will stay active. It has an internal pullup.

SDRAM7/PCI_STOP# - If MODE=1, this pin is a Synchronous DRAM DIMs clock output powered by Vddq3. If MODE=0, this pin is a PCI_STOP# input signal, where a low level stops the PCI clocks. It has an internal pull-up.

MODE - A low level on this pin causes pins 26, and 27 to be power management inputs PCI_STOP#, and CPU_STOP# respectly. A high level on this pin causes pins 26, and 27 to be clock output signals SDRAM7, and SDRAM6 respectively. It has an internal pull-up resistor.

PCICLK(0:5) - Low skew (<250pS) clock outputs for PCI frequencies. These buffers voltage level is controlled by Vddq3

PCICLK_F - A PCI clock output that does not stop until in power down mode. It is synchronous with other PCI clocks.

REF(0:2) - Buffered outputs of on-chip reference.

IOAPIC0 - Buffered output of 14.3MHZ for multiprocessor support. It is powered by Vddq2.

PWR_DWN# - Power down pin. When this pin is asserted low, the IC is in shutdown mode where all circuitry is turned off including VCO, crystal buffer and PCICLK_F. It has an internal pull-up. The I²C interface is disabled with the PWR_DWN# pin is low.

48/24MHz(0:1) - Programmable 48 MHZ or 24 MHZ clock outputs.

SDATA - serial data of I²C 2-wire control interface. Has internal pull-up resistor.

SDCLK - serial clock of I²C 2-wire control interface. Has internal pull-up resistor.

Vss - Ground pins for the chip.

Vdd - Power supply pins for analog circuit and core logic.

Vddq3 - Power supply pins for 3.3V IO pins.

Vddq2 - Power supply pins for 2.5V/3.3V IO pins.



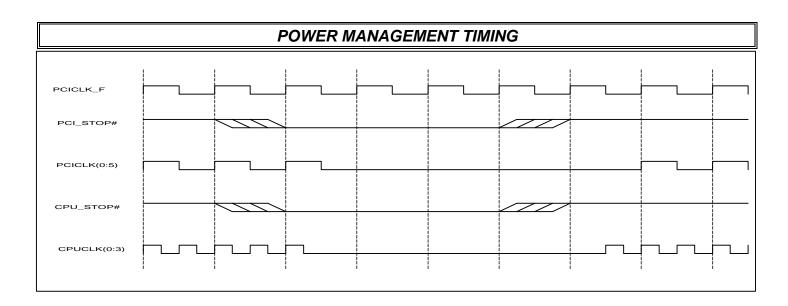
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POWER MANAGEMENT FUNCTIONS

All clocks can be individually enabled or stopped via the 2-wire control interface. All clocks are stopped in the low state. All clocks maintain a valid high period on transitions from running to stopped and on transitions from stopped to running when the chip was not powered down. On power up, the VCOs will stabilize to the correct pulse widths within about 0.2 mS. The CPU, SDRAM, and PCI clocks transition between running and stopped by waiting for one positive edge on PCICLK_F followed by a negative edge on the clock of interest, after which high levels of the output are either enabled or disabled.

When MODE=0, pins 26 and 27 are inputs PCI_STOP# and CPU_STOP# respectively (when MODE=1, these functions are not available). A particular output is enabled only when both the serial interface and these pins indicate that it should be enabled. The IMISC671 clocks may be disabled according to the following table in order to reduce power consumption. All clocks are stopped in the low state. All clocks maintain a valid high period on transitions from running to stopped. On low to high transitions of PWR_DWN#, external circuitry should allow 0.2 mS for the VCOs to stabilize prior to assuming the clock periods are correct. The CPU and PCI clocks transition between running and stopped by waiting for one positive edge on PCICLK_F followed by a negative edge on the clock of interest, after which high levels of the output are either enabled or disabled.

| CPU_STOP# | PCI_STOP# | PWR_DWN# | CPUCLK | PCICLK | OTHER CLKs | XTAL & VCOs |
|-----------|-----------|----------|-----------|-----------|------------|-------------|
| X | Х | 0 | LOW | LOW | LOW | OFF |
| 0 | 0 | 1 | LOW | LOW | RUNNING | RUNNING |
| 0 | 1 | 1 | LOW | 33/30 MHZ | RUNNING | RUNNING |
| 1 | 0 | 1 | 66/60 MHZ | LOW | RUNNING | RUNNING |
| 1 | 1 | 1 | 66/60 MHZ | 33/30 MHZ | RUNNING | RUNNING |





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2-WIRE I'C CONTROL INTERFACE

The 2-wire control interface implements a write only slave interface. The IMISC670 cannot be read back. Sub-addressing is not supported, thus all preceding bytes must be sent in order to change one of the control bytes. The 2-wire control interface allows each clock output to be individually enabled or disabled. It also allows 24/48 MHZ frequency selection and test mode enable.

During normal data transfer, the SDATA signal only changes when the SDCLK signal is low, and is stable when SDCLK is high. There are two exceptions to this. A high to low transition on SDATA while SDCLK is high is used to indicate the start of a data transfer cycle. A low to high transition on SDATA while SDCLK is high indicates the end of a data transfer cycle. Data is always sent as complete 8-bit bytes, after which an acknowledge is generated. The first byte of a transfer cycle is a 7-bit address with a Read/Write bit as the LSB. Data is transferred MSB first.

The device will respond to writes to 10 bytes (max) of data to address <u>D2</u> by generating the acknowledge (low) signal on the SDATA wire following reception of each byte. The device will not respond to any other control interface conditions. The I²C interface is disabled when the PWR_DWN# pin is low. Previously set control registers are retained.

SERIAL CONTROL REGISTERS

NOTE: The Pin# column lists the affected pin number where applicable. The @Pup column gives the state at true power up. Bytes are set to the values shown only on true power up, and not when the PWR_DWN# pin is activated.

Following the acknowledge of the Address Byte (D2), two additional bytes must be sent:

- 1) "Command Code " byte, and
- 2) "Byte Count" byte.

Although the data (bits) in these two bytes are considered "don't care", they <u>must be sent and will be</u> acknowledged.

Byte 0: Function Select Register (1 = enable, 0 = Stopped)

| Bit | @Pup | Pin# | Description | | |
|-----|------|------|---------------------|--|--|
| 7 | 0 | * | Reserved, Don't set | | |
| 6 | 0 | * | Reserved, Don't set | | |
| 5 | 0 | * | Reserved, Don't set | | |
| 4 | 0 | * | Reserved, Don't set | | |
| 3 | 1 | 23 | 48/24 Mhz | | |
| 2 | 1 | 22 | 48/24 Mhz | | |
| 1 | 0 | | Bit1 Bit0 | | |
| 0 | 0 | | 1 1 Tri-State | | |
| | | | 1 0 Reserved | | |
| | | | 0 1 Test Mode | | |
| | | | 0 0 Normal | | |

IMPORTANT NOTE

Reserved bits are intended for possible future functions. It is important that they be left at thie Power Up logic levels at all times. Otherwise data sheet specifications cannot be guaranteed.



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SERIAL CONTROL REGISTERS (Cont.)

Function Table

| Function | | Outputs | | | | | | |
|--------------|--------|---------|--------|--------|--------|--------|--------|--|
| Description | CPU | PCI | SDRAM | Ref | IOAPIC | 24MHZ | 48MHZ | |
| Tri-State | Hi-Z | Hi-Z | Hi-Z | Hi-Z | Hi-Z | Hi-Z | Hi-Z | |
| Test Mode | Tclk/2 | Tclk/4 | Tclk/2 | Tclk | Tclk | Tclk/4 | Tclk/2 | |
| Normal SEL=1 | 66 | CPU/2 | CPU | 14.318 | 14.318 | 24 | 48 | |
| Normal SEL=0 | 60 | CPU/2 | CPU | 14.318 | 14.318 | 24 | 48 | |

Notes:

- 1. Tclk is a test clock over driven on the Xin input during test mode.
- 2. The frequency ratio Fout/Fin for the USB output is 3.35294.

Byte 1: **CPU**, **48/24 MHz Clock Register (**1 = enable, 0 = Stopped)

| Bit | @Pup | Pin# | Description |
|-----|------|------|--------------------------|
| 7 | 1 | 23 | 48/24 MHz enable/Stopped |
| 6 | 1 | 22 | 48/24 MHz enable/Stopped |
| 5 | х | - | Reserved |
| 4 | Х | - | Reserved |
| 3 | 1 | 38 | CPUCLK3 enable/Stopped |
| 2 | 1 | 39 | CPUCLK2 enable/Stopped |
| 1 | 1 | 41 | CPUCLK1 enable/Stopped |
| 0 | 1 | 42 | CPUCLK0 enable/Stopped |

Byte 2: PCI Clock Register (1 = enable, 0 = Stopped)

| Bit | @Pup | Pin# | Description |
|-----|------|------|-------------------------|
| 7 | Х | - | Reserved |
| 6 | 1 | 8 | PCICLK_F enable/Stopped |
| 5 | 1 | 16 | PCICLK5 enable/Stopped |
| 4 | 1 | 14 | PCICLK4 enable/Stopped |
| 3 | 1 | 13 | PCICLK3 enable/Stopped |
| 2 | 1 | 12 | PCICLK2 enable/Stopped |
| 1 | 1 | 11 | PCICLK1 enable/Stopped |
| 0 | 1 | 9 | PCICLK0 enable/Stopped |



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SERIAL CONTROL REGISTERS(Continued)

Byte 3: SDRAM Clock Register (1 = enable, 0 = Stopped)

| Bit | @Pup | Pin# | Description |
|-----|------|------|-----------------------|
| 7 | 1 | 26 | SDRAM7 enable/Stopped |
| 6 | 1 | 27 | SDRAM6 enable/Stopped |
| 5 | 1 | 29 | SDRAM5 enable/Stopped |
| 4 | 1 | 30 | SDRAM4 enable/Stopped |
| 3 | 1 | 32 | SDRAM3 enable/Stopped |
| 2 | 1 | 33 | SDRAM2 enable/Stopped |
| 1 | 1 | 35 | SDRAM1 enable/Stopped |
| 0 | 1 | 36 | SDRAM0 enable/Stopped |

Byte 4: Additional SDRAM Clock Register (1 = enable, 0 = Stopped)

| Bit | @Pup | Pin# | Description |
|-----|------|------|-------------|
| 7 | Х | - | Reserved |
| 6 | Х | - | Reserved |
| 5 | Х | - | Reserved |
| 4 | Х | - | Reserved |
| 3 | Х | - | Reserved |
| 2 | Х | - | Reserved |
| 1 | Х | - | Reserved |
| 0 | Х | - | Reserved |

Byte 5: Peripheral Control (1 = enable, 0 = Stopped)

| Bit | @Pup | Pin# | Description |
|-----|------|------|------------------------|
| 7 | Х | - | Reserved |
| 6 | Х | • | Reserved |
| 5 | 1 | • | Reserved |
| 4 | 1 | 45 | IOAPIC0 enable/Stopped |
| 3 | x | - | Reserved |
| 2 | 1 | 47 | REF2 enable/Stopped |
| 1 | 1 | 1 | REF1 enable/Stopped |
| 0 | 1 | 2 | REF0 enable/Stopped |



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SERIAL CONTROL REGISTERS(Continued)

Byte 6: Reserved Register

| Bit | @Pup | Pin# | Description |
|-----|------|------|-------------|
| 7 | Х | • | Reserved |
| 6 | х | - | Reserved |
| 5 | Х | - | Reserved |
| 4 | Х | - | Reserved |
| 3 | Х | • | Reserved |
| 2 | х | - | Reserved |
| 1 | Х | - | Reserved |
| 0 | Х | - | Reserved |

Byte 7: Frequency Control

If the three LSBs of this register are 111 (as at power up), the frequency is controlled by the SEL package pin. Note that if this pin is open, the internal pull-up will select 66 MHz. Otherwise, the CPU clock frequency is controlled by F_SEL(0:2).

| Bit | @Pup | Description |
|-----|------|-------------|
| 7 | Х | Reserved |
| 6 | Х | Reserved |
| 5 | Х | Reserved |
| 4 | Х | Reserved |
| 3 | Х | Reserved |
| 2 | 1 | F_SEL2 |
| 1 | 1 | F_SEL1 |
| 0 | 1 | F SEL0 |

| FSEL2 | FSEL1 | FSEL0 | FREQUENCY |
|-------|-------|-------|--------------|
| 0 | 0 | 0 | Reserved |
| 0 | 0 | 1 | Reserved |
| 0 | 1 | 0 | Reserved |
| 0 | 1 | 1 | 33 MHz |
| 1 | 0 | 0 | 50 MHz |
| 1 | 0 | 1 | 55 MHz |
| 1 | 1 | 0 | 60 MHz |
| 1 | 1 | 1 | From SEL pin |





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MAXIMUM RATINGS

Voltage Relative to VSS:

Voltage Relative to VDD:

Storage Temperature:

-65°C to + 150°C

Ambient Temperature:

-55°C to +125°C

Maximum Power Supply:

7V

This device contains circuitry to protect the inputs against damage due to high static voltages or electric field; however, precautions should be taken to avoid application of any voltage higher than the maximum rated voltages to this circuit. For proper operation, Vin and Vout should be constrained to the range:

VSS<(Vin or Vout)<VDD

Unused inputs must always be tied to an appropriate logic voltage level (either VSS or VDD).

| ELECTRICAL CHARACTERISTICS | | | | | | | | | |
|----------------------------------|--------|-----|-----|-----|-------|--|--|--|--|
| Characteristic | Symbol | Min | Тур | Max | Units | Conditions | | | |
| Input Low Voltage | VIL | - | - | 0.8 | Vdc | - | | | |
| Input High Voltage | VIH | 2.0 | - | - | Vdc | - | | | |
| Input Low Current | IIL | | | -66 | μA | | | | |
| Input High Current | IIH | | | 5 | μA | | | | |
| Output Low Voltage | VOL | - | - | 0.4 | Vdc | All Outputs (see buffer spec) | | | |
| IOL = 4mA | | | | | | | | | |
| Output High Voltage IOH = 4mA | VOH | 2.4 | - | - | Vdc | All Outputs Using 3.3V Power (see buffer spec) | | | |
| Tri-State leakage Current | loz | - | - | 10 | μA | | | | |
| Dynamic Supply Current | ldd | - | - | 90 | mA | CPU = 66.6 MHz, PCI = 33.3 MHz | | | |
| Static Supply Current | Isdd | - | - | 150 | μA | - | | | |
| Short Circuit Current | ISC | 25 | - | - | mA | 1 output at a time - 30 seconds | | | |

 $VDD = VDDQ3 = 3.3V \pm 5\%$, VDDQ2 = 2.375V to 2.9V, $TA = 0^{\circ}C$ to $+70^{\circ}C$



²C Clock Generator for Pentium Notebook Designs.

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| SWITCHING CHARACTERISTICS | | | | | | | | |
|--|-------------------|-----|-----|--------------|-------|---|--|--|
| Characteristic | Symbol | Min | Тур | Max | Units | Conditions | | |
| Output Duty Cycle | - | 45 | 50 | 55 | % | Measured at 1.5V | | |
| CPU to PCI Offset | tOFF | 1 | - | 4 | ns | 15 pf Load Measured at 1.5V | | |
| Buffer out Skew All CPU and PCI Buffer Outputs | tSKEW | - | - | 250 | ps | 15 pf Load Measured at 1.5V | | |
| ΔPeriod Adjacent Cycles | ΔΡ | - | - | <u>+</u> 250 | ps | - | | |
| Jitter Spectrum 20 dB Bandwidth from Center | BWJ | | | 500 | KHz | | | |
| Overshoot/Undershoot Beyond Power Rails | V _{over} | - | - | 1.5 | V | 22 ohms @ source of 8 inch PCB run to 15 pf load | | |
| Ring Back Exclusion | V_{RBE} | 0.7 | | 2.1 | V | note1 | | |
| $VDD = VDDQ3 = 3.3V \pm 5\%$, $VDDQ2 = 2.375V$ to 2.9V, $TA = 0^{\circ}C$ to $+70^{\circ}C$ | | | | | | | | |

note 1: Ring Back must not enter this range.

| TYPE 1 BUFFER CHARACTERISTICS FOR CPUCLK(0:3) | | | | | | | |
|---|--------------------|-----|-----|-----|-------|--------------|--|
| Characteristic | Symbol | Min | Тур | Max | Units | Conditions | |
| Pull-Up Current Min | IOH _{min} | -27 | - | - | mA | Vout = 1.0 V | |
| Pull-Up Current Max | IOH _{max} | - | - | -27 | mA | Vout = 2.6 V | |
| Pull-Down Current Min | IOL_{min} | 27 | - | - | mA | Vout = 1.2 V | |
| Pull-Down Current Max | IOL _{max} | - | - | 27 | mA | Vout = 0.3 V | |
| Rise/Fall Time Min Between 0.4 V and 2.0 V | TRF _{min} | 0.4 | - | - | nS | 10 pF Load | |
| Rise/Fall Time Max Between 0.4 V and 2.0 V | TRF _{max} | - | - | 1.6 | nS | 20 pF Load | |

 $VDD = VDDQ3 = 3.3V \pm 5\%$, VDDQ2 = 2.375V to 2.9V, $TA = 0^{\circ}C$ to $+70^{\circ}C$

 $VDD = VDDQ3 = 3.3V \pm 5\%$, VDDQ2 = 2.375V to 2.9V, $TA = 0^{\circ}C$ to $+70^{\circ}C$

| TYPE 2 BUFFER CHARACTERISTICS FOR IOAPIC | | | | | | | |
|--|--------------------|-----|-----|-----|-------|--------------|--|
| Characteristic | Symbol | Min | Тур | Max | Units | Conditions | |
| Pull-Up Current Min | IOH _{min} | -27 | - | - | mA | Vout = 1.4 V | |
| Pull-Up Current Max | IOH _{max} | - | - | -19 | mA | Vout = 2.7 V | |
| Pull-Down Current Min | IOL _{min} | 24 | - | - | mA | Vout = 1.0 V | |
| Pull-Down Current Max | IOL _{max} | - | - | 19 | mA | Vout = 0.2 V | |
| Rise/Fall Time Min Between 0.4 V and 2.0 V | TRF _{min} | 0.4 | - | - | nS | 10 pF Load | |
| Rise/Fall Time Max Between 0.4 V and 2.0 V | TRF _{max} | - | - | 1.6 | nS | 20 pF Load | |



²C Clock Generator for Pentium Notebook Designs.

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| TYPE 3 BUFFER CHARACTERISTICS FOR REF(1:2) and 48/24 MHz | | | | | | | |
|---|--------------------|-----|---|-----|------------|----------------|--|
| Characteristic Symbol Min Typ Max Units Conditions | | | | | | | |
| Pull-Up Current Min | IOH _{min} | -29 | - | - | mA | Vout = 1.0 V | |
| Pull-Up Current Max | IOH _{max} | - | - | -23 | mA | Vout = 3.135 V | |
| Pull-Down Current Min | IOL _{min} | 29 | - | - | mA | Vout = 1.95 V | |
| Pull-Down Current Max | IOL _{max} | - | - | 27 | mA | Vout = 0.4 V | |
| Rise/Fall Time Min Between 0.4 V and 2.4 V | TRF _{min} | 1.0 | - | - | nS | 10 pF Load | |
| Rise/Fall Time Max Between 0.4 V and 2.4 V TRF _{max} 4.0 nS 20 pF Load | | | | | 20 pF Load | | |
| VDD = VDDQ3 = 3 3V +5% VDDQ2 = 2 375V to 2 9V TA = 0°C to ±70°C | | | | | | | |

 $VDD = VDDQ3 = 3.3V \pm 5\%$, VDDQ2 = 2.375V to 2.9V, $TA = 0^{\circ}C$ to $+70^{\circ}C$

 $VDD = VDDQ3 = 3.3V \pm 5\%$, VDDQ2 = 2.375V to 2.9V, $TA = 0^{\circ}C$ to $+70^{\circ}C$

| TYPE 4 BUFFER CHARACTERISTICS FOR REF0 and SDRAM(0:7) | | | | | | | |
|--|--------------------|-----|---|------------|----|----------------|--|
| Characteristic Symbol Min Typ Max Units Conditions | | | | | | | |
| Pull-Up Current Min | IOH _{min} | -51 | - | - | mA | Vout = 1.65 V | |
| Pull-Up Current Max | IOH _{max} | - | - | -46 | mA | Vout = 3.135 V | |
| Pull-Down Current Min | IOL _{min} | 54 | - | - | mA | Vout = 1.65 V | |
| Pull-Down Current Max | IOL _{max} | - | - | 53 | mA | Vout = 0.4 V | |
| Rise/Fall Time Min Between 0.4 V and 2.4 V TRF _{min} 0.5 nS 20 pF Load | | | | 20 pF Load | | | |
| Rise/Fall Time Max Between 0.4 V and 2.4 V TRF _{max} 1.3 nS 30 pF Load | | | | | | | |
| $VDD = VDDQ3 = 3.3V \pm 5\%$, $VDDQ2 = 2.375V$ to 2.9V, $TA = 0^{\circ}C$ to $+70^{\circ}C$ | | | | | | | |

TYPE 5 BUFFER CHARACTERISTICS FOR PCICLK(0:5,F) **Symbol** Units **Conditions** Characteristic Min Тур Max Vout = 1.0 V Pull-Up Current Min IOH_{min} -33 mΑ $V_{out} = 3.135 \text{ V}$ **Pull-Up Current Max** IOH_{max} -33 mΑ IOL_{min} Vout = 1.95 V Pull-Down Current Min 30 mΑ **Pull-Down Current Max** IOL_{max} Vout = 0.4 V38 mΑ Rise/Fall Time Min Between 0.4 V and 2.4 V 15 pF Load $\mathsf{TRF}_{\mathsf{min}}$ 0.5 nS Rise/Fall Time Max Between 0.4 V and 2.4 V TRF_{max} 2.0 nS 30 pF Load



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| | CRYST | AL AND | REFERENC | E OSCILLA | ATOR PA | RAMETERS |
|--------------------------------------|------------|--------|----------|-----------|---------|---|
| Characteristic | Symbol | Min | Тур | Max | Units | Conditions |
| Frequency | Fo | 12.00 | 14.31818 | 16.00 | MHz | |
| Tolerence | TC | - | - | +/-100 | PPM | Calibration note 1 |
| | TS | - | - | +/- 100 | PPM | Stability (Ta -10 to +60C) note 1 |
| | TA | - | - | 5 | PPM | Aging (first year @ 25C) note 1 |
| Mode | ОМ | - | - | - | | Parallell Resonant |
| Pin Capacitance | СР | | 6 | | pF | Capacitance of XIN and Xout pins to ground (each) |
| DC Bias Voltage | V_{BIAS} | 0.3Vdd | Vdd/2 | 0.7Vdd | V | |
| Startup time | Ts | - | - | 30 | μS | |
| Load Capacitance | CL | - | 20 | - | pF | the crystals rated load. note 1 |
| Effective Series resonant resistance | R1 | - | - | 40 | Ohms | |
| Power Dissipation | DL | - | - | 0.10 | mW | note 1 |
| Shunt Capacitance | СО | - | | 8 | pF | crystals internal package capacitance (total) |

For maximum accuracy, the total circuit loading capacitance should be equal to CL. This loading capacitance is the effective capacitance across the crystal pins and includes the device pin capacitance (CP) in parallel with any circuit traces, the clock generator and any onboard discrete load capacitors.

Budgeting Calculations

Typical trace capacitance, (< half inch) is 4 pF, Load to the crystal is therefore

Clock generator internal pin capacitance of 36 pF, Load to the crystal is therefore

External crystal loading capacitors (connect to ground)

15.0 pF

the total parasitic capacitance would therefore be

Note 1: It is recommended but not manditory that a crystal meets these specifications.



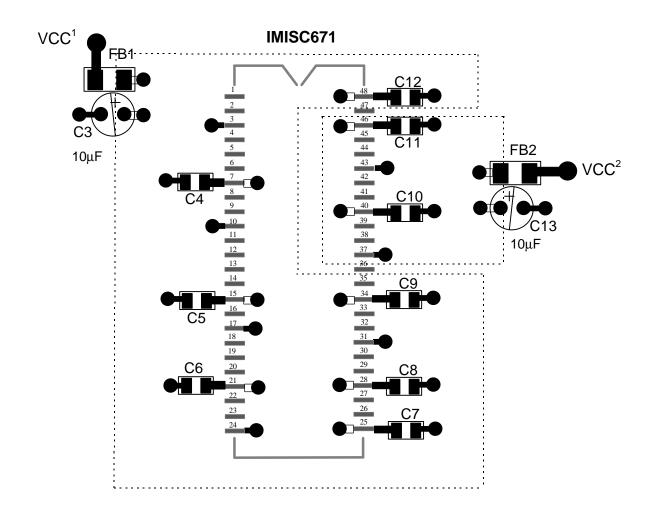
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PCB LAYOUT SUGGESTION

Via to VDD Island

Via to GND plane

Via to VCC plane

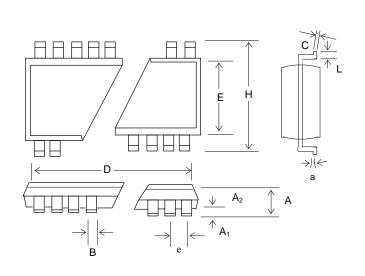


This is only a layout recommendation for best performance and lower EMI. The designer may choose a different approach but C4, C5, C6, C7, C8, C9, C10, C11and C12 (all are $0.1\mu f$) should always be used and placed close to their VDD pins.



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PACKAGE DRAWING AND DIMENSIONS



| 48 P | 48 PIN SSOP OUTLINE DIMENSIONS | | | | | | | | | |
|----------------|--------------------------------|-----------|--------|-------------|-----------|-------|--|--|--|--|
| | | INCHES | | MILLIMETERS | | | | | | |
| SYMBOL | MIN | NOM | MAX | MIN | NOM | MAX | | | | |
| Α | 0.095 | 0.102 | 0.110 | 2.41 | 2.59 | 2.79 | | | | |
| A ₁ | 0.008 | 0.012 | 0.016 | 0.20 | 0.31 | 0.41 | | | | |
| A2 | 0.088 | 0.090 | 0.092 | 2.24 | 2.29 | 2.34 | | | | |
| В | 0.008 | 0.010 | 0.0135 | 0.203 | 0.254 | 0.343 | | | | |
| С | 0.005 | - | 0.010 | 0.127 | - | 0.254 | | | | |
| D | 0.620 | 0.625 | 0.630 | 15.75 | 15.88 | 16.00 | | | | |
| Е | 0.292 | 0.296 | 0.299 | 7.42 | 7.52 | 7.59 | | | | |
| е | | 0.025 BS0 | | C |).635 BS(| | | | | |
| Н | 0.400 | 0.406 | 0.410 | 10.16 | 10.31 | 10.41 | | | | |
| а | 0.10 | 0.013 | 0.016 | 0.25 | 0.33 | 0.41 | | | | |
| L | 0.024 | 0.032 | 0.040 | 0.61 | 0.81 | 1.02 | | | | |
| а | 00 | 5° | 80 | 00 | 5° | 8º | | | | |
| X | 0.085 | 0.093 | 0.100 | 2.16 | 2.36 | 2.54 | | | | |

| ORDERING INFORMATION | | | | | | |
|----------------------|--|--|--|--|--|--|
| Part Number | Part Number Package Type Production Flow | | | | | |
| IMISC671CYB | C671CYB 48 PIN SSOP Commercial, 0°C to +70°C | | | | | |

Note: The ordering part number is formed by a combination of device number, device revision, package style, and screening as shown below.

Marking:

Example:

SC671CYB

Date Code, Lot #

IMISC671CYB B = Commercial, 0°C to + 70°C Package Y = SSOP Revision

IMI Device Number